

## IN THE CLAIMS

The following is a complete listing of the claims, and replaces all earlier listings and all earlier versions.

1. (Currently Amended) A positioning system for dental x-ray examinations, comprising:
  - an electronic image sensor;
  - a sheath covering the electronic image sensor; and
  - a holder removably bonded to the sheath by an a pressure sensitive adhesive,

wherein the pressure sensitive adhesive enables the holder to be applied to and removed from the sheath by a dental practitioner.
2. (Previously Presented) The positioning system as set forth in Claim 1, wherein the electronic image sensor comprises a charge-coupled device.
3. (Previously Presented) The positioning system as set forth in Claim 1, wherein the electronic image sensor comprises a CMOS active pixel sensor array.
4. (Previously Presented) The positioning system as set forth in Claim 1, wherein the holder is bonded to the sheath at any point along a surface of the electronic image sensor.

5. (Previously Presented) The positioning system as set forth in Claim 1, wherein the sheath is a material selected from the group consisting of paper, cotton, sponge, rubber, plastic, latex, and nylon.

6. (Previously Presented) The positioning system as set forth in Claim 1, wherein the adhesive is selected from the group consisting of tape, epoxy, hot melt, and sealant.

7. (Currently Amended) A method for positioning enabling a dental practitioner to position an electronic dental image sensor, comprising the steps of:

- placing the electronic sensor in a sheath;
- affixing a holder having an a pressure sensitive adhesive coating to the sheath to create a removable bond between the holder and the sheath;
- positioning the holder and the electronic sensor within the mouth of patient;
- capturing at least one dental image; and
- removing the holder from the sheath following the capture of the at least one dental image.

8. (Previously Presented) The method as set forth in Claim 7, wherein the holder is bonded to the sheath at any point along a surface of the electronic image sensor.

9. (Previously Presented) The method as set forth in Claim 7, wherein the sheath is a material selected from the group consisting of paper, cotton, sponge, rubber, plastic, latex, and nylon.

10. (Previously Presented) The method as set forth in Claim 7, wherein the adhesive is selected from the group consisting of tape, epoxy, hot melt, and sealant.

11. (Currently Amended) A positioning system for dental x-ray examinations, comprising:

an electronic image sensor; and

a holder removably bonded to the electronic image sensor by ~~an a~~ pressure sensitive adhesive coating,

wherein the pressure sensitive adhesive coating enables the holder to be applied to and removed from the electronic image sensor by a dental practitioner.

12-13. (Canceled)

14. (Previously Presented) The dental positioning system as set forth in Claim 11, wherein the electronic image sensor comprises a CMOS active pixel sensor array.

15. (Previously Presented) The dental positioning system as set forth in Claim 11, wherein the electronic image sensor comprises a charge-coupled device.

16. (Canceled)

17. (Previously Presented) The dental positioning system as set forth in Claim 11, wherein the adhesive is selected from the group consisting of tape, epoxy, hot melt, and sealant.

18. (Currently Amended) A method for positioning enabling a dental practitioner to position an electronic dental image sensor, comprising steps of:

affixing a holder having an a pressure sensitive adhesive coating to the electronic image sensor to create a removable bond between the holder and the electronic image sensor;

positioning the holder and the electronic image sensor within the mouth of a patient;

capturing at least one dental image; and

removing the holder from the electronic image sensor following the capture of at lease one dental image.

19. (Previously Presented) The method as set forth in Claim 18, wherein the electronic image sensor comprises a CMOS active pixel sensor array.

20. (Previously Presented) The method as set forth in Claim 18, wherein the electronic image sensor comprises a charge-coupled device.

21. (Previously Presented) The method as set forth in Claim 18, wherein the adhesive is selected from the group consisting of tape, epoxy, hot melt, and sealant.